Winstar Display Co., LTD 華凌光電股份有限公司



住址: 407 台中市中清路 163 號 No.163 Chung Ching RD., Taichune, Taiwan, R.O.C

WEB: http://www.winstar.com.tw
E-mail: sales@winstar.com.tw
Tel:886-4-24262208 Fax: 886-4-24262207

SPECIFICATION

CUST	OME	R :_				
MODU	W	024	0128A-	TFH#		
APPR	OVE	D BY:				
(FOR CUST	OMER	USE ONLY	7)	PC	B VERSION:	DATA:
SALES E	ВҮ	APPROV	/ED BY	СНІ	ECKED BY	PREPARED BY
VERSION	Ε	PATE	REVISE PAGE N		SUI	MMARY
0	2010).07.09		Fi	rst issue	



MODLE NO:

REC	CORDS OF RE	DOC. FIRST ISSUE	
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2010.07.09		First issue

Contents

- 1. Module Classification Information
- 2. Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing
- 9. Timing Characteristics
- 10. Display Command
- 11.Reliability
- 12.Backlight Information
- 13. Inspection specification
- 14. Material List of Components for RoHs
- 15. Storage

1.Module Classification Information

$$\underline{\underline{W}} \underline{O}$$
 $\underline{240128}$ $\underline{A} - \underline{\underline{T}} \underline{F} \underline{\underline{H}}$ $\underline{\#}$ $\underline{\$}$ $\underline{\$}$ $\underline{\$}$ $\underline{\$}$

- ① Brand: WINSTAR DISPLAY CORPORATION
- ② Display Type: H→Character Type, G→Graphic Type O→COG Type
- 3 Display Font: 240 x 128 dots
- Model serials no.

 $\ \$ Backlight Type: N \rightarrow Without backlight T \rightarrow LED, White

 $B \rightarrow EL$, Blue green $A \rightarrow LED$, Amber $D \rightarrow EL$, Green $R \rightarrow LED$, Red $W \rightarrow EL$, White $O \rightarrow LED$, Orange $F \rightarrow CCFL$, White $G \rightarrow LED$, Green $Y \rightarrow LED$, Yellow Green $P \rightarrow LED$, Blue

© LCD Mode: $B\rightarrow TN$ Positive, Gray $T\rightarrow FSTN$ Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev.

3.General Specification

Item	Dimension	Unit
Number of Characters	240 x 128 dots	_
Module dimension	98.7x 67.7 x9.5	mm
View area	92.0 x 53.0	mm
Active area	83.975 x 44.775	mm
Dot size	0.325 x0.325	mm
Dot pitch	0.35 x 0.35	mm
LCD type	FSTN Positive, Transflective (In LCD production, It will occur slightly color can only guarantee the same color in the same b	
Duty	1/128 , 1/12 Bias	
View direction	6 o'clock	
Backlight Type	LED White	

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	$V_{\rm IN}/V_{\rm OUT}$	-0.3	_	V _{DD} +0.3	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3		4.0	V
LCD Driver Supply Voltage	V_{LCD}	-0.3		+18.0	V

5.Electrical Characteristics

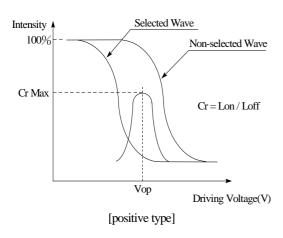
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	2.7	3.0	3.3	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	V_{DD} - V_5	Ta=25°℃	_	15.5	_	V
		Ta=70°C	_	_	_	V
Supply Current(No include	I_{DD}	V _{DD} =3.0V		1.1		mA
LED Backlight)						

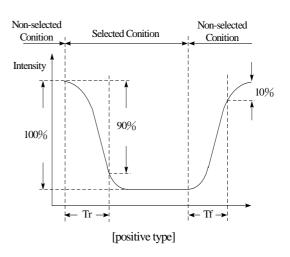
6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	30	_	60	deg
View Aligie	(H) φ	CR≧2	-45	_	45	deg
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



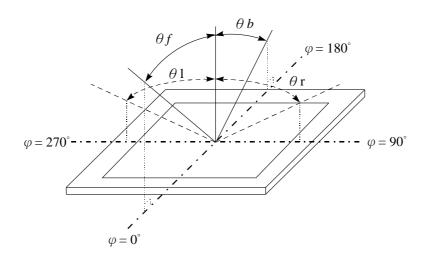


Conditions:

Operating Voltage : Vop Viewing Angle(θ , φ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle($CR \ge 2$)

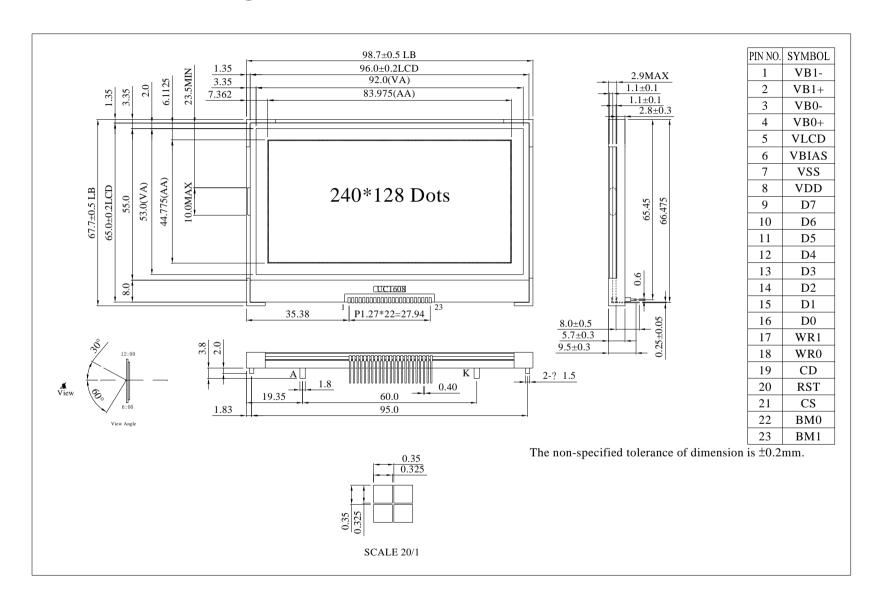


Page 7/27

7.Interface Pin Function

Pin No.	Symbol	Type	Description
1	VB1-		
2	VB1+	PWR	LCD Bias Voltages. These voltages are always generated
3			internally. Connect capacitors of CB value between VBX+ to VBX+.
4	VB0+		
5	$ m V_{LCD}$	PWR	Main LCD Power Supply. When internal VLCD is used, connect these pins together. When external VLCD source is used, connect external VLCD source to VLCD-IN pins and leave VLCDOUT open. A by-pass capacitor CL should be connected between VLCD and VSS.
6	V_{BIAS}		Reference voltages to generate the actual seg driving voltages
7	V_{SS}	PWR	Ground
8	V_{DD}	PWR	Supply Voltage for logic
9	D7		
10	D6		Bi-directional bus for both serial and parallel host interfaces.
11	D5		Connect unused pins to VSS in serial modes. When PS1="L", D0: SCK (serial clock),
12	D4	I/O	D2: SDI (input data),
13	D3	1/0	D4: SDO (output data), D1, D3, D5~7: High impedance, connect to VSS.
14	D2		When PS1="H", D[7:0] is under the control of WR[1:0] and CS[1:0]
15	D1		WK[1.0] and CS[1.0]
16	D0		
17	WR1	I	WR[1:0] controls the read/write operation of the host interface. In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode.
18	WR0		In serial interface modes, these two pins are not used. Connect to VSS.
19	CD	I	Select Control data or Display data for read/write operation. When in serial 9-bit mode, this pin is not used, connect to VSS. "L": Control data "H": Display data
20	RST	I	When RST="L", all control registers are reinitialized by their default states and/or by their pin configurations if applicable. When RST is not used, connect the pin to VDD1.
21	CS	I	Chip Select. Chip selected when CE="H".
22	BM0	т	Bus modes:
23	BM1	I	Serial modes: "LL": SPI 2-bit serial mode. Parallel modes: "HL": 8080 "HH": 6800

8.Contour Drawing



9. Timing Characteristics

Please consult the spec of UC1608

10. Display Command

The following is a list of host commands support by UC1608

C/D: 0: Control, 1: Data

W/R: 0: Write Cycle, 1: Read Cycle

Useful Data bits

- Don't Care

Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	
Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte @ PA/CA	
Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte @ PA/CA	
Get Status	0	1	ΒZ	MX	DE	RS	0	0	0	0	Get Status Summary	
Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA[3:0]=D[3:0]	
Set Column Address MSB	0	0	0	0	0	1	#	#	#	#	Set CA[7:4] =D[3:0]	
Set Mux rate & Gain Parameter. ¹⁾	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set GN[1:0]=D[1:0]	
Set Mux rate & Temperature Compensation. ²⁾	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set TC[1:0]=D[1:0]	
Set Power Control	0	0	0	0	1	0	1	#	#	#	Set PC[2:0]=D[2:0]	
Set Adv. Program Control	0	0	0	0	1	1	0	0	F	?	Set APC[R][7:0]=D[7:0],	
(double byte command)	0	0	#	#	#	#	#	#	#	#	where R = 00, or 01	
Set Start Line	0	0	0	1	#	#	#	#	#	#	Set SL[5:0]=D[5:0]	
Set V _{REF} potential meter (double-byte command) ¹⁾	0	0	1 #	0 #	0 #	0 #	0 #	0 #	0 #	1 #	Set PM[5:0]=D[5:0] Set TC[1:0]=D[7:6]	
Set V _{REF} potential meter (double-byte command) ²⁾	0	0	1 #	0	0 #	0 #	0 #	0 #	0 #	1 #	Set PM[5:0]=D[5:0] Set GN[1:0]=D[7:6]	
Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]=D[2:0]	
Set Serial Bus Control	0	0	1	0	0	1	0	0	#	#	Set BC[1:0]=D[1:0]	
Set Column Mirroring	0	0	1	0	1	0	0	0	0	#	Set LC[2]=D0	
Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]=D0	
Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]=D0	
Set Display ON/OFF	0	0	1	0	1	0	1	#	#	#	Set DC[4:2]=D[2:0]	
Set Page Address	0	0	1	0	1	1	#	#	#	#	Set PA[3:0]=D[3:0]	
Set LCD to RAM Mapping	0	0	1	1	0	0	#	#	#	#	Set LC[3:0]=D[3:0]	
System Reset	0	0	1	1	1	0	0	0	1	0	System Reset sequence	
NOP	0	0	1	1	1	0	0	0	1	1	No operation	
Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]= D[1:0]	
Reset Cursor Update Mode	0	0	1	1	1	0	1	1	1	0	Set AC[3]=0, CA=CR;	
Set Cursor Update Mode	0	0	1	1	1	0	1	1	1 1		Set AC[3]=1, CR=CA;	
Set Test Control (double byte command)	0	0	1 #	1 #	1 #	0 #	0 #	1 #	# #	T #	For testing only. Do not use.	

11.Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

	Environmental Test								
Test Item	Content of Test	Test Condition	Note						
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2						
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2						
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs							
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1						
High Temperature/ Humidity Operation	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2						
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles							
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3						
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k Ω CS=100pF 1 time							

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

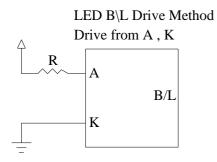
12.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	1200	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity (Without LCD)	IV	480	600	_	CD/M2	ILED=96mA
Wave Length	X	0.26	0.28	0.3		ILED=96mA
,	Y	0.28	0.3	0.32		ILLD-John
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED ≤ 96mA 25°C ,50-60%RH, (Note 1)
Color	White	I	l	I		

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



13. Inspection specification

NO	Item	Criterion						
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 						
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 						
03	LCD black spots, white spots, contamination (non-display)	$ \begin{array}{c c} & \Phi \leq 0.10 & Acc\\ \hline 0.10 < \Phi \leq 0.20 & \\ \hline 0.20 < \Phi \leq 0.25 & \\ \hline 0.25 < \Phi & \\ \hline \end{array} $ 3.2 Line type : (As following drawing)	eptable Q TY ept no dense 2 1 0 ptable Q TY					
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	ept no dense 2 round type					
04	Polarizer bubbles	judge using black spot	ept no dense 3 2 0 3					

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blac	ck spots, white spots, con	ntamination	
		k: Seal width t:L: Electrode pad length6.1 General glass chip :	Glass thickness a: LC	ip thickness ED side length panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a	
06	glass	$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a	2.5
		6.1.2 Corner crack:	chips, x is total length of	y	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x ≤ 1/8a	
		$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a	
		⊙ If there are 2 or more	chips, x is the total lengtl	n of each chip.	

NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		$\begin{array}{ c c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\\hline y \leq 0.5mm & x \leq 1/8a & 0 < z \leq t \\\hline 6.2.2 \ Non-conductive portion: \\\hline \end{array}$	
06	Glass crack	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		 ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. 	
		y: width x: length	
		$y \le 1/3L$ $x \le a$	
		У	

NO	Item	Criterion	AQL	
07	Cracked glass The LCD with extensive crack is not acceptable.		2.5	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65	
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5	
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	

NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

14. Material List of Components for RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

•

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limi	ted value is s	et up accord	ing to RoHS	•		

2.Process for RoHS requirement:

(1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. $: 235\pm5^{\circ}\mathbb{C}$;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

15. Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

	· · · · · · · · · · · · · · · · · · ·	<u>le Estimat</u>	e Feedback Sheet	
Modul	e Number:			Page: 1
1 \ <u>P</u>	anel Specification:			
1.	Panel Type:	Pass	☐ NG ,	
2.	View Direction:	Pass	☐ NG ,	
3.	Numbers of Dots:	Pass	☐ NG ,	
4.	View Area:	Pass	☐ NG ,	
5.	Active Area:	Pass	☐ NG ,	
6.	Operating Temperature:	Pass	□ NG ,	
7.	Storage Temperature:	Pass	☐ NG ,	
8.	Others:			
2 · <u>N</u>	<u>Mechanical Specification</u> :			
1.	PCB Size:	Pass	□ NG ,	
2.	Frame Size:	Pass	☐ NG ,	
3.	Materal of Frame:	Pass	☐ NG ,	
4.	Connector Position:	Pass	☐ NG ,	
5.	Fix Hole Position: A	Pass	☐ NG ,	
6.	Backlight Position:	Pass	☐ NG ,	
7.	Thickness of PCB:	Pass	☐ NG ,	
8.	Height of Frame to PCB:	Pass	☐ NG ,	
9.	Height of Module:	Pass	☐ NG ,	
10.	Others:	Pass	☐ NG ,	
3 \ <u>R</u>	Relative Hole Size :			
1.	Pitch of Connector:	Pass	☐ NG ,	
2.	Hole size of Connector:	Pass	☐ NG ,	
3.	Mounting Hole size:	Pass	☐ NG ,	
4.	Mounting Hole Type:	Pass	☐ NG ,	
5.	Others:	Pass	☐ NG ,	
4 \ <u>B</u>	acklight Specification:			
1.	B/L Type:	Pass	☐ NG ,	
2.	B/L Color:	Pass	☐ NG ,	
3.	B/L Driving Voltage (Refere	nce for LED	Type): Pass	□ NG ,
4.	B/L Driving Current:	Pass	☐ NG ,	
5.	Brightness of B/L:	Pass	☐ NG ,	
6.	B/L Solder Method:	Pass	☐ NG ,	
7.	Others:	Pass	☐ NG ,	

 $>> \,$ Go to page 2 $\,<<$

Number:		Page: 2	
Electronic Characteristics of	f Module :		
Input Voltage:	Pass	☐ NG ,	
Supply Current:	Pass	□ NG ,	
Driving Voltage for LCD:	Pass	□ NG ,	
Contrast for LCD:	Pass	☐ NG ,	
B/L Driving Method:	Pass	□ NG ,	
Negative Voltage Output:	Pass	☐ NG ,	
Interface Function:	Pass	□ NG ,	
LCD Uniformity:	Pass	□ NG ,	
ESD test:	Pass	☐ NG ,	
Others:	Pass	☐ NG ,	
Sales signature : Customer Signature :			